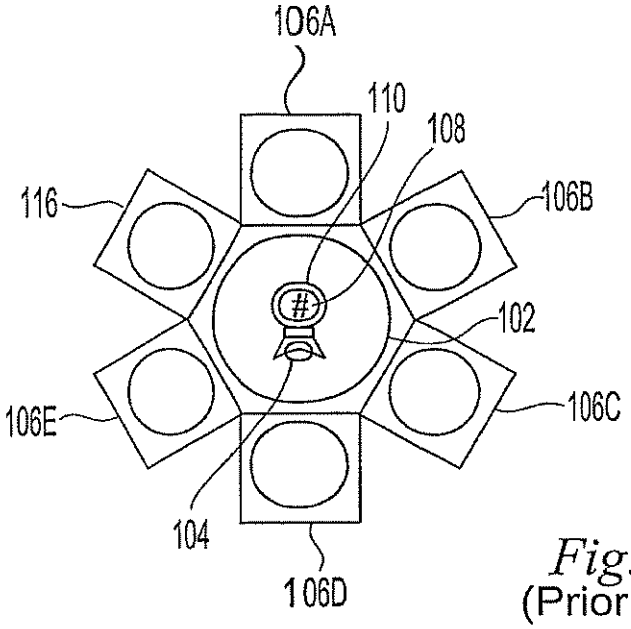
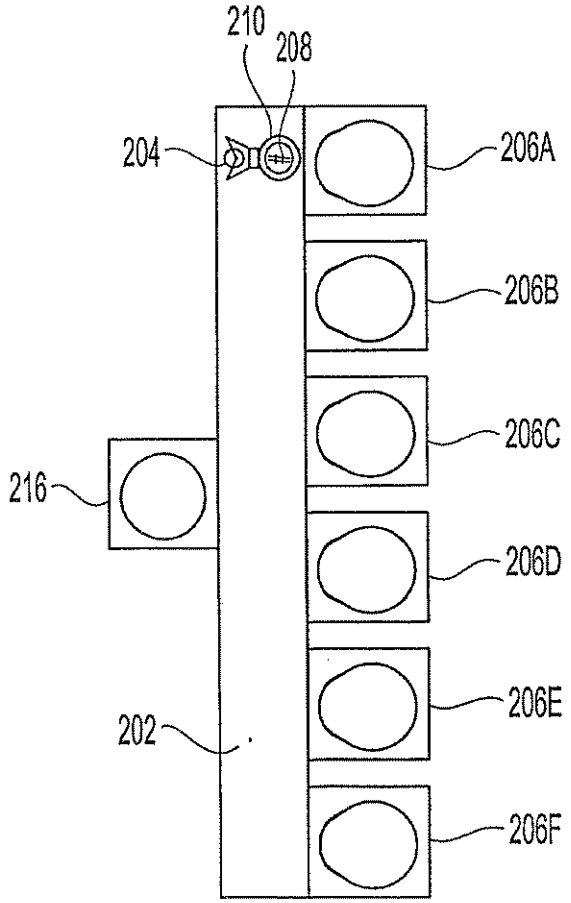


100

Fig. 1
(Prior Art)



200

Fig. 2
(Prior Art)

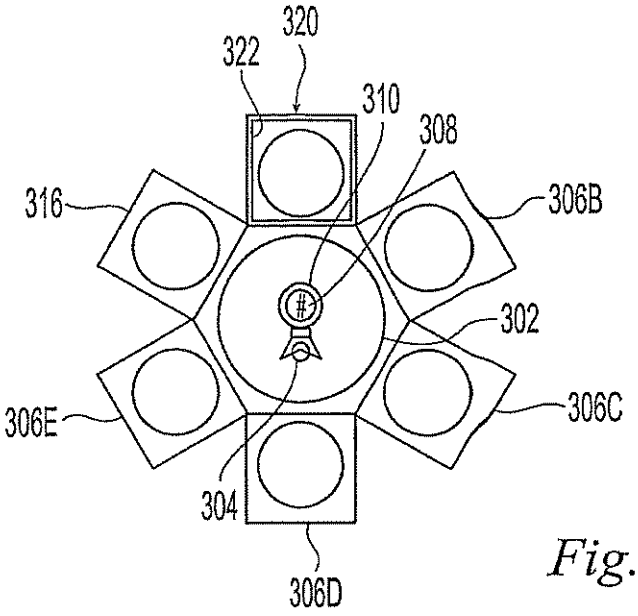

300
320
322
310
308
316
306B
302
306E
306C
304
306D

Fig. 3

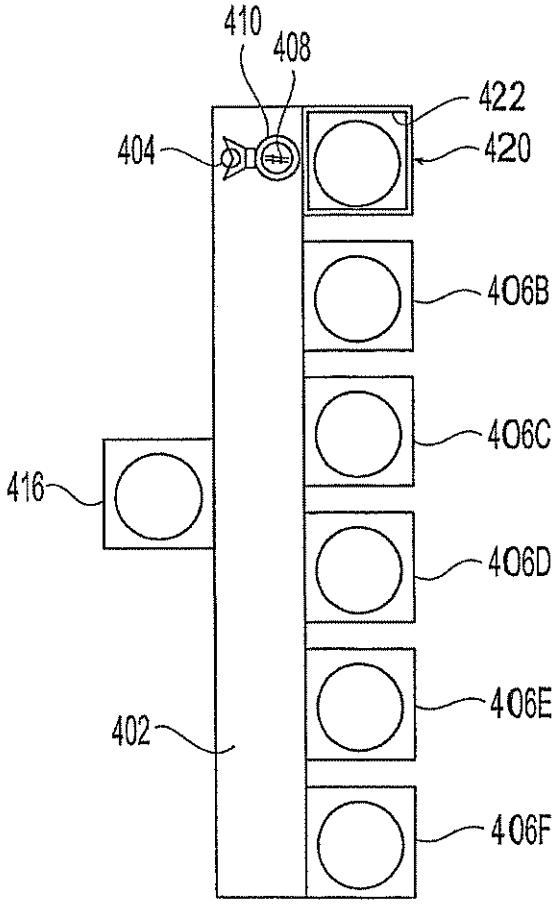

400
410
408
422
404
420
406B
406C
416
406D
406E
402
406F

Fig. 4

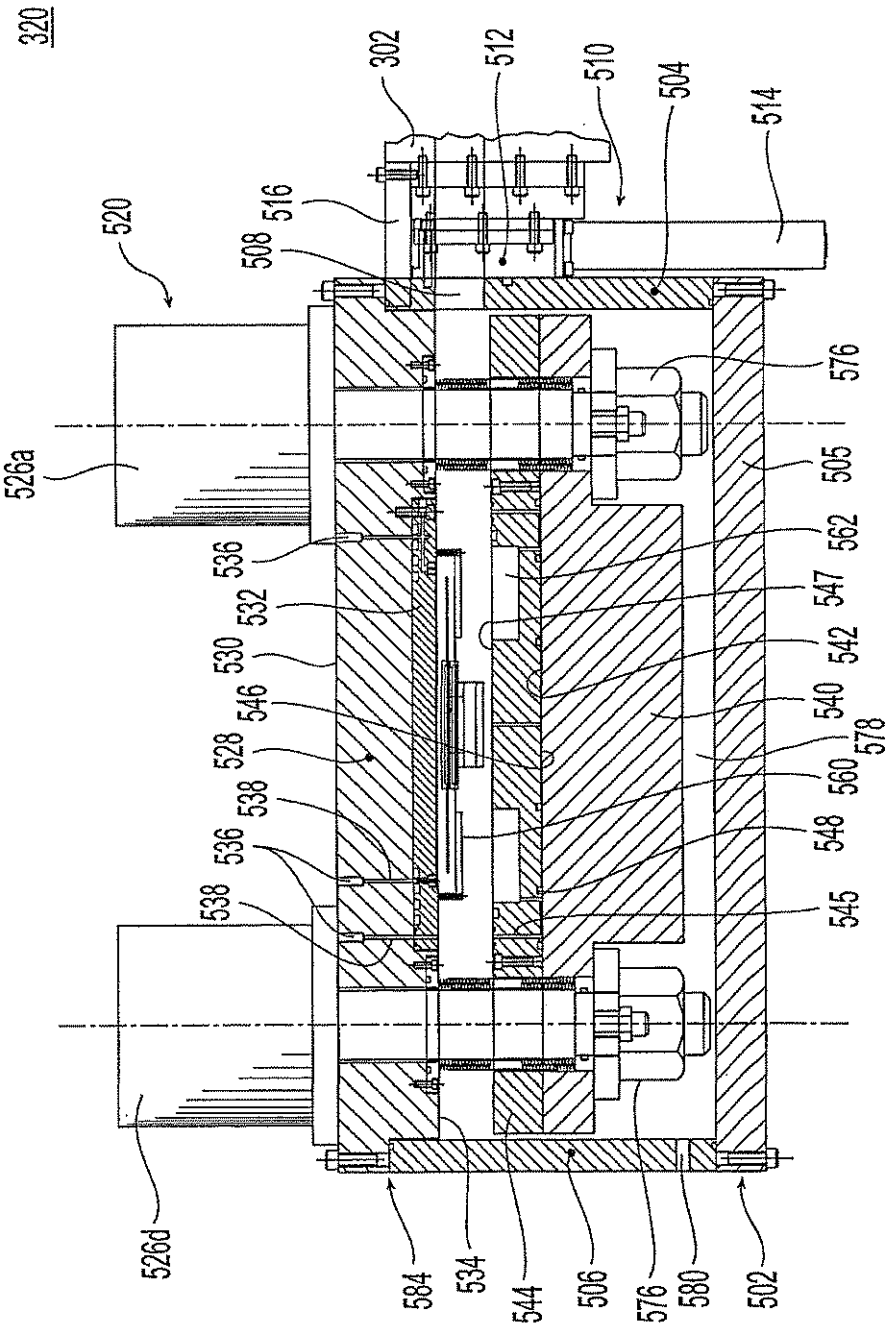

320
302
512
510
504
514
516
508
520
576
526a
505
562
536
547
532
542
530
540
546
578
528
560
538
548
536
545
538
526d
584
534
544
506
576
580
502

Fig. 5

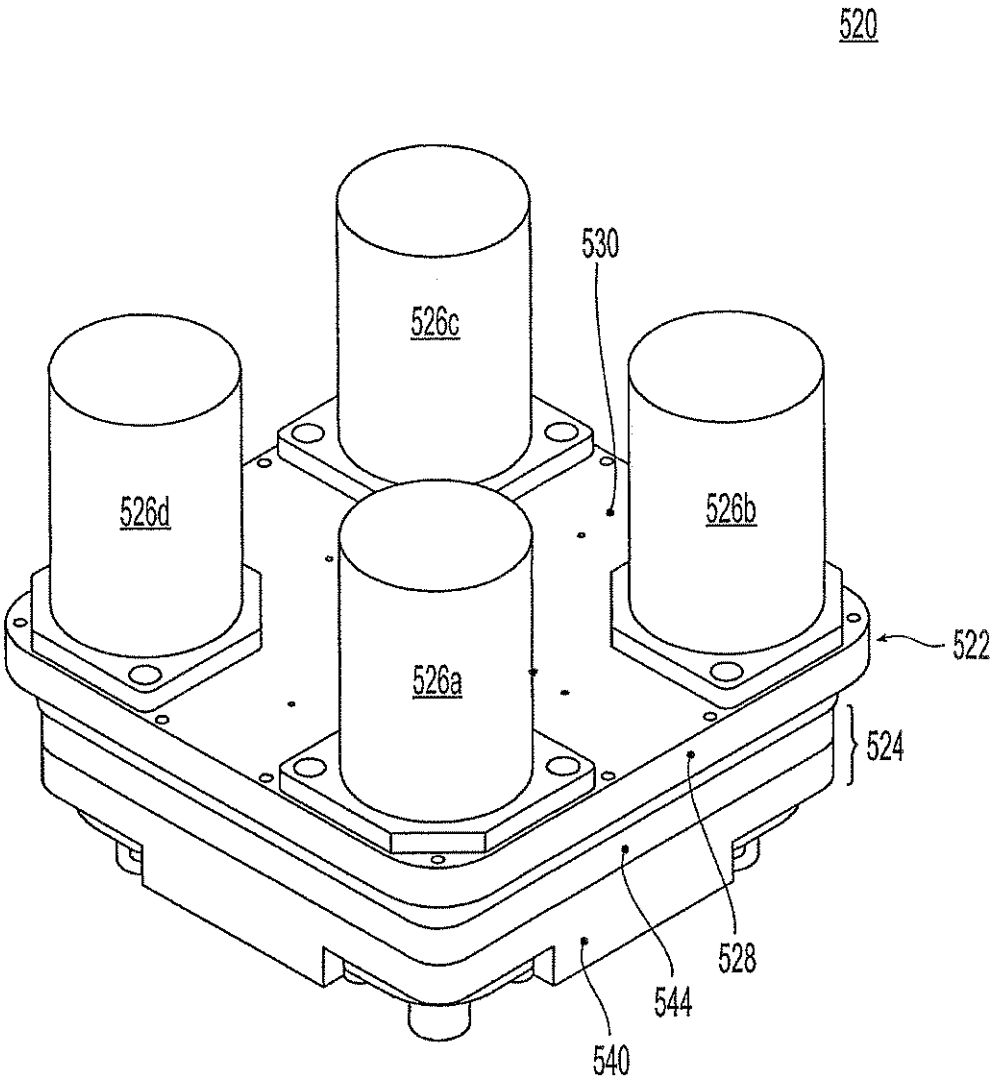


Fig. 6

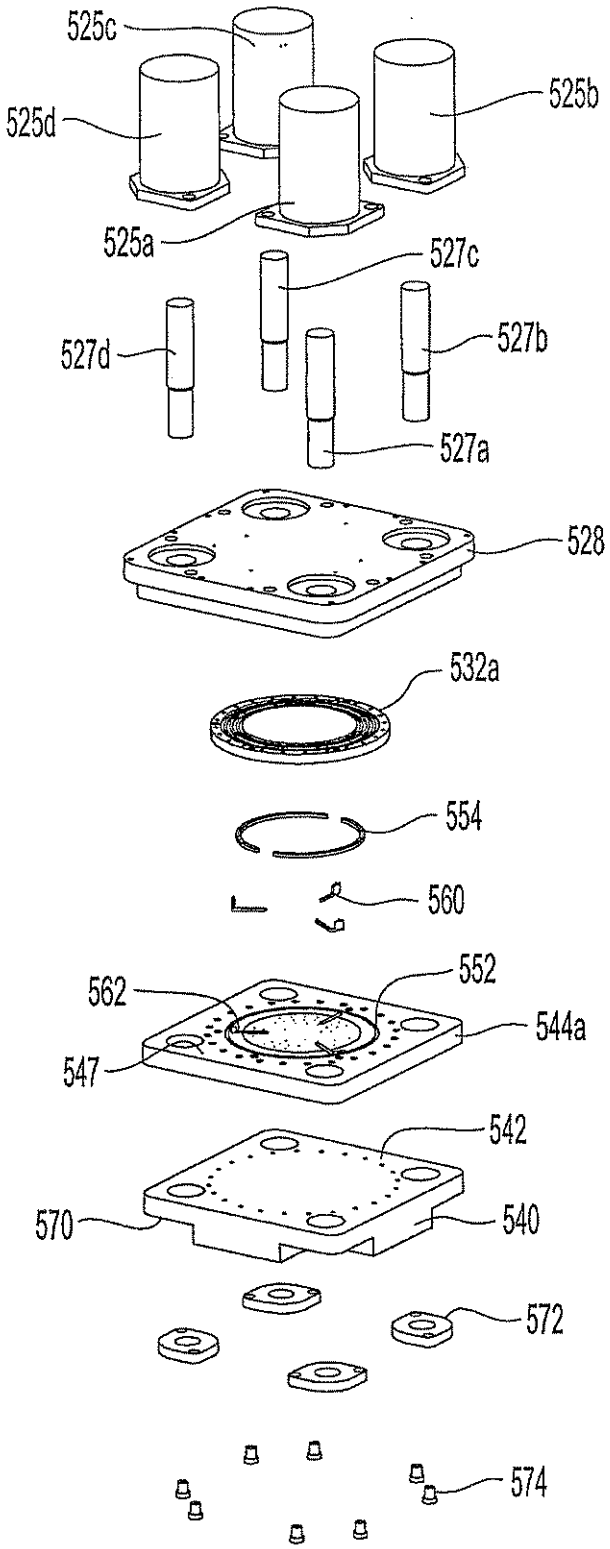

525c
525b
525d
525a
527c
527d
527b
527a
528
532a
554
560
562
552
544a
547
542
570
540
572
574

Fig. 7

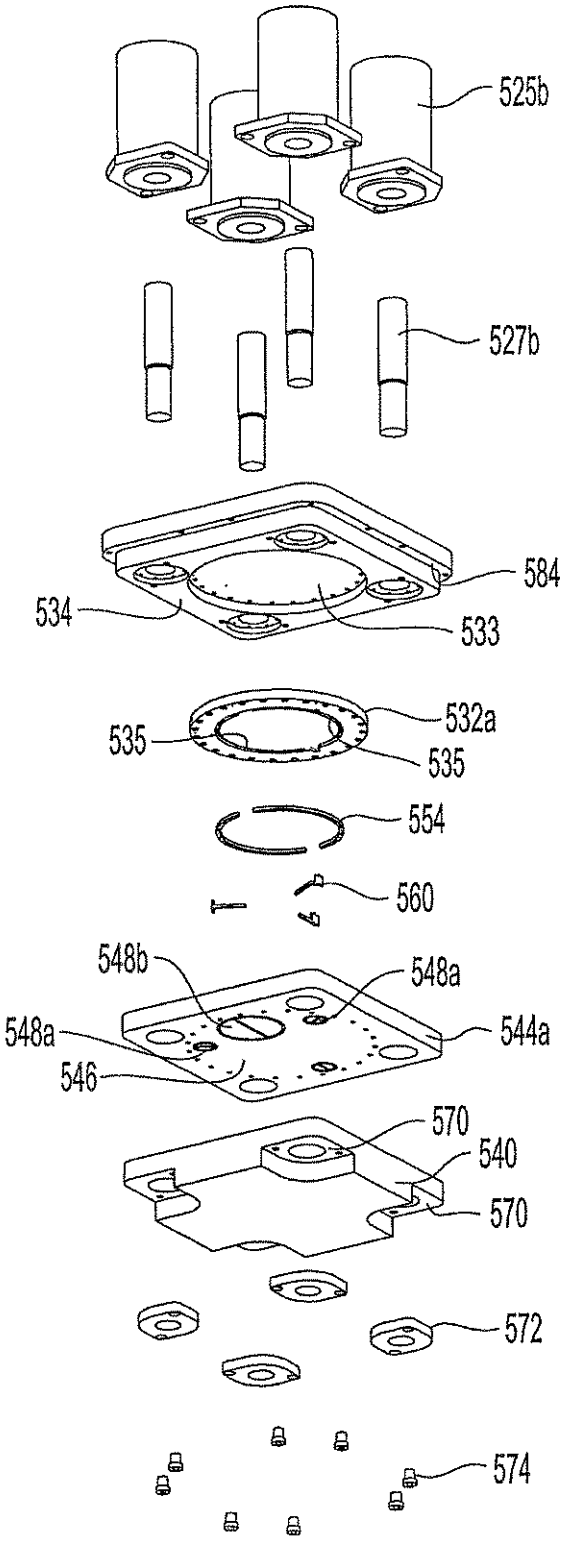

525b
527b
584
534
533
535
532a
535
554
560
548b
548a
548a
544a
546
570
540
570
572
574

Fig. 8

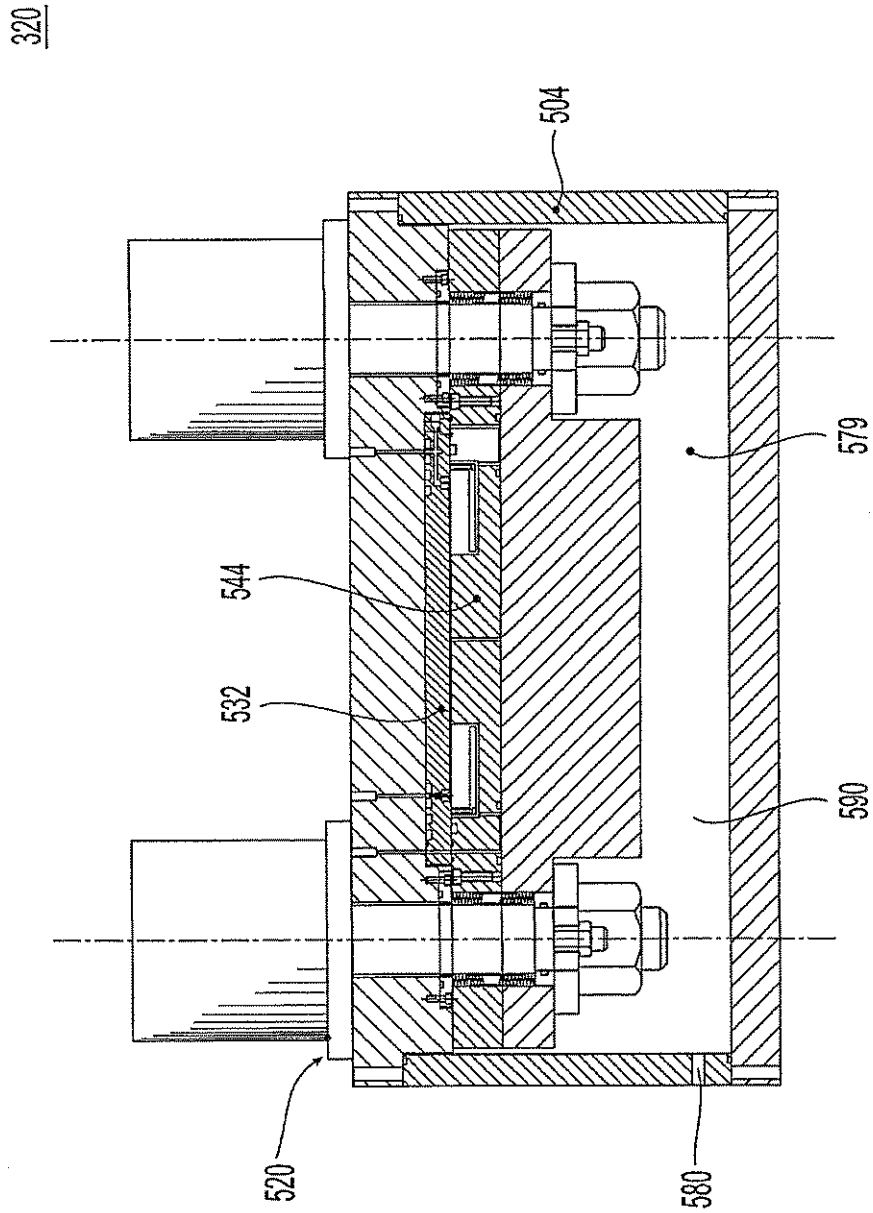


Fig. 9

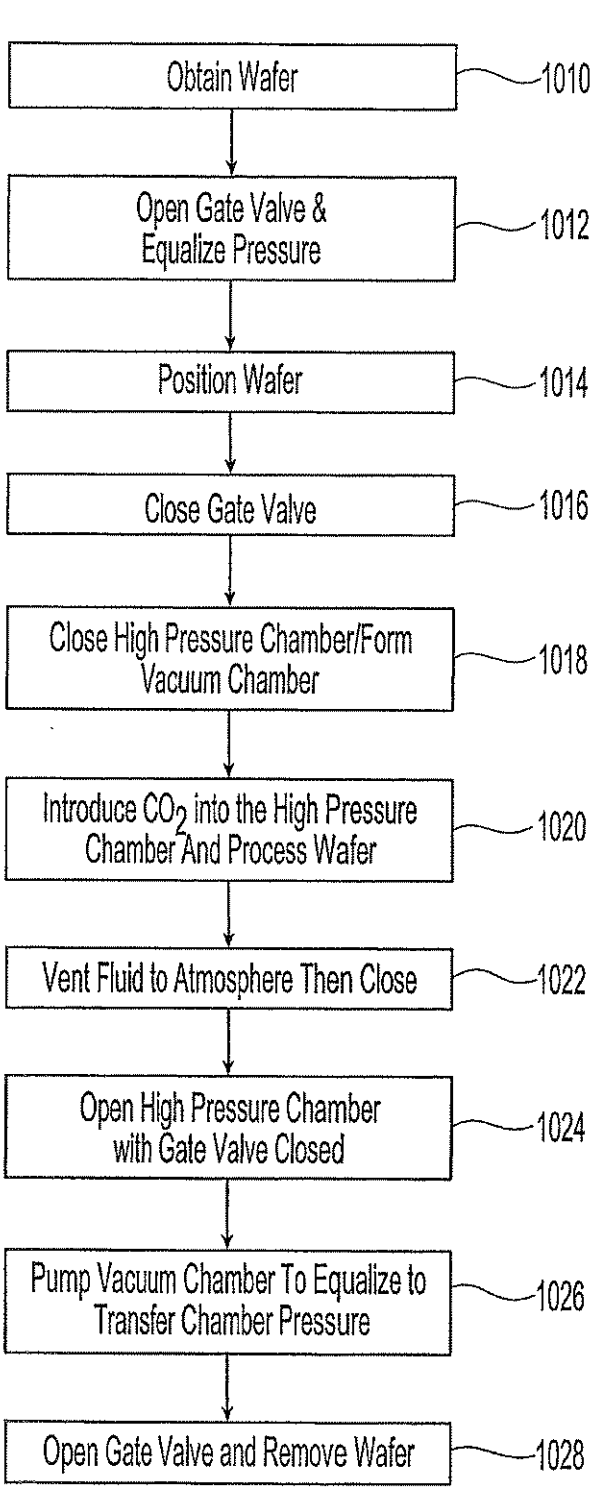

1000
Obtain Wafer
1010
Open Gate Valve & Equalize Pressure
1012
Position Wafer
1014
Close Gate Valve
1016
Close High Pressure Chamber/Form Vacuum Chamber
1018
Introduce CO_2 into the High Pressure Chamber And Process Wafer
1020
Vent Fluid to Atmosphere Then Close
1022
Open High Pressure Chamber with Gate Valve Closed
1024
Pump Vacuum Chamber To Equalize to Transfer Chamber Pressure
1026
Open Gate Valve and Remove Wafer
1028

Fig. 10